



Material Content Data Sheet



Sales Product Name		SAB-C161PI-LM CA		Issued		27. September 2017		
MA#		MA000733216						
Package		PG-MQFP-100-2		Weight*		1786.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	16.129	0.90	0.90	9026	9026
leadframe	non noble metal	magnesium	7439-95-4	0.538	0.03		301	
	inorganic material	silicon	7440-21-3	2.331	0.13		1304	
	non noble metal	nickel	7440-02-0	10.756	0.60		6019	
	non noble metal	copper	7440-50-8	344.917	19.30	20.06	193018	200642
wire	noble metal	gold	7440-57-5	3.785	0.21	0.21	2118	2118
encapsulation	organic material	carbon black	1333-86-4	6.916	0.39		3870	
	plastics	epoxy resin	-	200.572	11.22		112242	
	inorganic material	silicondioxide	60676-86-0	1175.768	65.82	77.43	657968	774080
leadfinish	non noble metal	tin	7440-31-5	19.520	1.09	1.09	10924	10924
plating	noble metal	silver	7440-22-4	1.857	0.10	0.10	1039	1039
glue	plastics	epoxy resin	-	0.970	0.05		543	
	noble metal	silver	7440-22-4	2.910	0.16	0.21	1628	2171
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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